TOSHIBA Bipolar Linear Integrated Circuit Silicon Monolithic

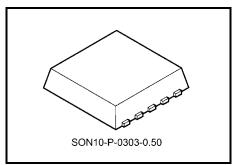
TA6009FM

Shock Sensor IC (1 ch version)

TA6009FM detects an existence of external shock through the shock sensor and output.

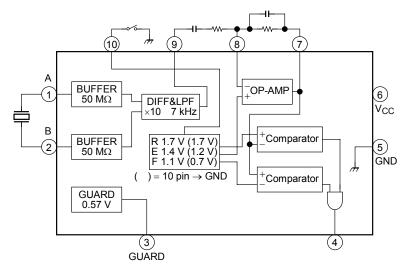
Features

- TA6009FM operates from 2.7 to 5.5 V DC single power supply voltage.
- Signal from the shock sensor is amplified according to setting gain, and is detected through the internal window comparator.
- TA6009FM incorporates 1-ch shock detecting circuitry.
- Input terminal of sensor signal is designed high impedance. Differential input impedance = 100 M Ω (typ.)
- LPF (Low Pass Filter) circuitry is incorporated. Cut-off frequency of LPF = 7 kHz
- Sensitivity of shock detection can be adjusted by external devices.
- Small package SON10-P-0303-0.50 (0.5 mm pitch)

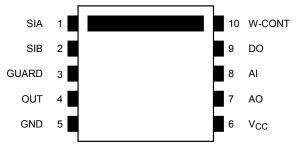


Weight: 0.016 g (typ.)

Block Diagram



Pin Connection (top view)



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Pin Function

Pin No.	Pin Name	Function
1	SIA	Connection terminal of shock sensor
2	SIB	Connection terminal of shock sensor
3	GUARD	Input (1, 2 pin) GUARD terminal
4	OUT	Output terminal (output = "L" when shock is detected.)
5	GND	Ground terminal
6	V_{CC}	Power supply voltage
7	AO	Op-Amp output terminal
8	Al	Op-Amp input terminal
9	DO	Differential-Amp output terminal
10	W-CONT	WindComp. trip voltage selection terminal

Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Power supply voltage	V _{CC}	7	٧	
Power dissipation	P _D	150	mW	
Storage temperature	T _{stg}	-55 to 150	°C	

Recommend Operating Condition

Characteristics	Symbol	Rating	Unit
Power supply voltage	V _{CC}	2.7 to 5.5	٧
Operating temperature	T _{opr}	-25 to 85	°C

Note: The IC may be destroyed due to short circuit between adjacent pins, incorrect orientation of device's mounting, connecting positive and negative power supply pins wrong way round, air contamination fault, or fault by improper grounding.

Electrical Characteristics (unless otherwise specified, $V_{CC} = 3.3 \text{ V}$, $Ta = 25^{\circ}\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Supply voltage	V _C C	_	_	2.7	3.3	5.5	V
Supply current	laa	(1)	V _{CC} = 3.3 V		1.8	2.4	- mA
Зарріу сипені	ICC		V _{CC} = 5.0 V		1.8	2.4	ША

(GUARD)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output voltage	VoGur	(2)	_	0.52	0.57	0.62	V

(DIFF-AMP)

Characteristics		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Input impedance	(Note 1)	Zin	_	_	50	100		MΩ
Gain		GvBuf	(3)	_	19.6	20	20.4	dB
Output DC voltage		VoBuf	(4)	Connect C = 100 pF between 1 pin and 2 pin	0.7	1	1.3	٧
Low pass filter cut-off freq.		fc	(5)	Frequency at -3dB point	5	7	10	kHz
Output source current		IBso	(6)	Voh = V _{CC} – 1 V	400	800		μА
Output sink current		IBsi	(7)	Vol = 0.3 V	75	130		μΑ

Note 1: Marked parameters are reference data.

(OP-AMP)

Characteristics		Symbol	Test Circuit	Test Condition		Min	Тур.	Max	Unit
Cut-off frequency	(Note 1)	fT	_	_	_		2		MHz
Openloop gain	(Note 1)	Gvo	_	_		80	90		dB
Input voltage 1		Vin1	(8)	10 pin → OPEN (Note 2)		1.33	1.4	1.47	V
Input voltage 2		Vin2	(9)	10 pin \rightarrow GND (Note 2)		1.14	1.2	1.26	V
Input current		l _{in}	(10)	_			25	50	nA
Offset voltage	(Note 1)	Voff	_	_		-5	0	5	mV
Output source current		IAso	(11)	$Voh = V_{CC} - 1 V$		300	800		μА
Output sink current		IAsi	(12)	Vol = 0.3 V		130	200		μА

Note 1: Marked parameters are reference data.

(Window-comparator)

Characteristics		Symbol	Test Circuit	Test Condition		Min	Тур.	Max	Unit
Trip voltage 1	(Note 1)	Vtrp1	_	10 pin → OPEN	(Note 2)	Vin1 ±0.285	Vin1 ±0.3	Vin1 ±0.315	٧
Trip voltage 2	(Note 1)	Vtrp2	_	10 pin → GND	(Note 2)	Vin2 ±0.475	Vin2 ±0.5	Vin2 ±0.525	V
Output source current		IWso	(13)	$Voh = V_{CC} - 0.5 V$		30	50		μА
Output sink current		IWsi	(14)	Vol = 0.3 V		300	800		μΑ

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Note 1: Marked parameters are reference data.

Note 2: 10 pin must be non-connected otherwise connected to GND.

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Application Note

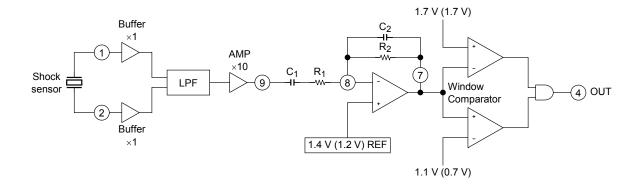


Figure 1 The configuration of G-force sensor amplifier

Figure 1 is the composition of G-Force sense amplifier.

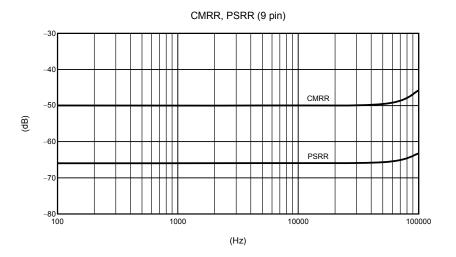
The shock sensor is connected between 1 and 2 terminal.

When G-force Sensor (sensor sensibility = s (mV/G)) is used to detect external shock of g (G), the external parts are determined as following.

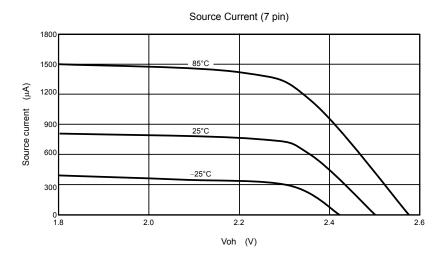
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(Gain setting) * 10 PIN \rightarrow GND 500/(s × g) = G1 G1/10 = G (OP-AMP) (HPF setting) fc = 1/(2 \pi × R<sub>1</sub> × C<sub>1</sub>) (LPF setting) fc = 1/(2 \pi × R<sub>2</sub> × C<sub>2</sub>)
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Reference Data

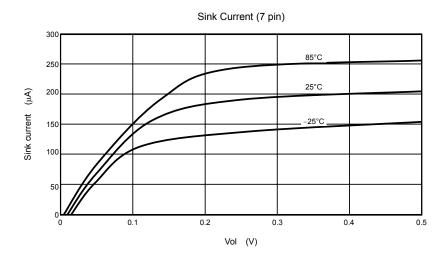
(1) 9 pin (DIFF-AMP output) CMRR, PSRR



(2) 7 pin (OP-AMP output) source current

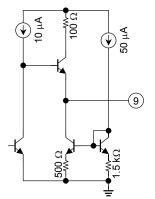


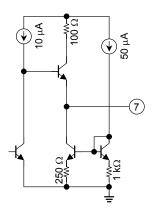
(3) 7 pin (OP-AMP output) sink current

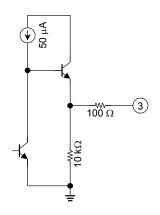


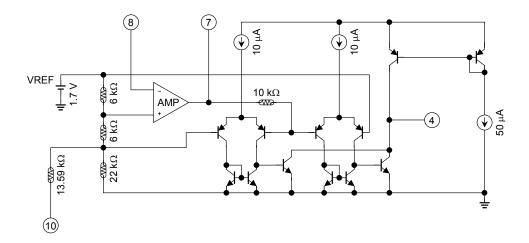
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Equivalent Circuit





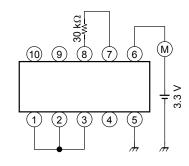




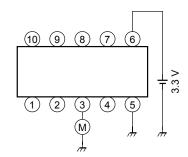
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Test Circuit

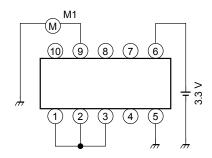
(1) Supply current ICC



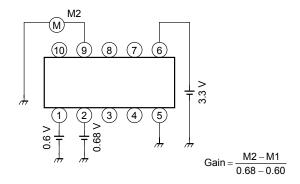
 $\begin{array}{cc} \text{(2)} & \text{GUARD} \\ & \text{Output voltage } \textbf{VoGur} \end{array}$



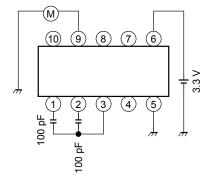
(3) DIFF-AMP Gain **GvBuf** Step 1



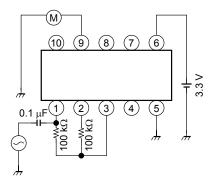
Step 2



(4) DIFF-AMP Output DC voltage **VoBuf**

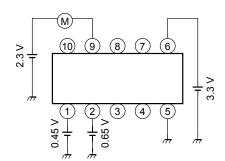


(5) DIFF-AMP Low pass filter cut-off freq. $\bf fc$

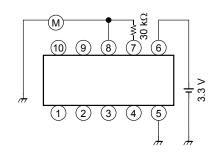


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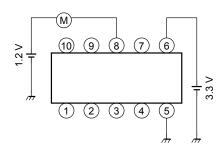
(6) DIFF-AMP Output source current **IBso**



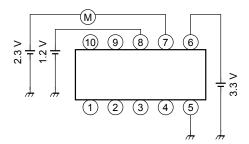
(8) OP-AMP Input voltage 1 **Vin1**



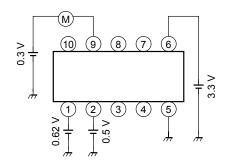
(10) OP-AMP Input current **I**in



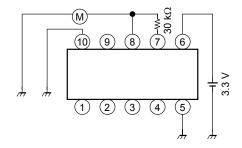
(11) OP-AMP
Output source current IAso



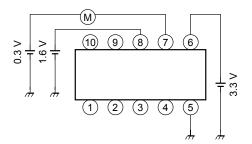
(7) DIFF-AMP Output sink current **IBsi**



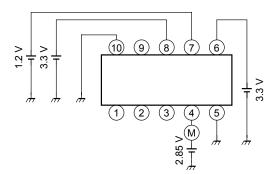
(9) OP-AMP Input voltage 2 **Vin2**



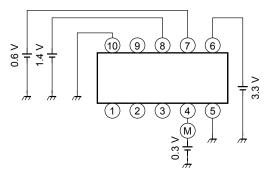
(12) OP-AMP Output sink current **IAsi**



(13) Window comparator Output source current **IWso**

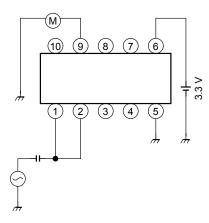


(14) Window comparator Output sink current **IWsi**

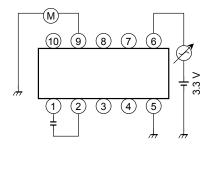


Test Circuit (for reference)

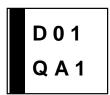
(a) DIFF-AMP **CMRR**



(b) DIFF-AMP **PSRR**



Marking



Week 1-26

D 0 1
Q A 1

Week 27-53

D 0 1

D01: Product number Q: Monthly and Weekly code

A1: Lot code

Mold material: Epoxy resin

Lead material and disposition: An alloy of copper, soldering

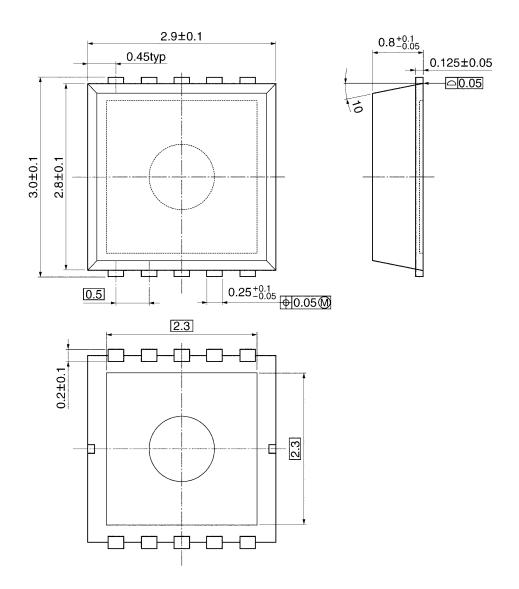
Production country: JAPAN

Production factory: Front end process TOSHIBA Kitakyushu factory

Back end process TOSHIBA Kitakyushu factory

Package Dimensions

SON10-P-0303-0.50 Unit: mm



Weight: 0.016 g (typ.)

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